




Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32MP135FAF7	2B40*501XXXY	A	9991	13-07-2023
	Amount	UoM	Unit type	ST ECOPACK Grade
	370.00	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant ( in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used or other bulk termination : add in comments	NAC	Copper Alloy	SACN305	

Package Designator	Size	Nbr of instances	Shape	
BGA	11x11	320	bulk solder	
Comment	Package : B0EC TFBGA 11X11 320L PITCH 0.5 MM DM00699790			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-10 Jun 2022				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	2B40*501XXXY				6000000.0	1000000.6				
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Die or dies	M-011 Other inorganic materials	7.106	mg	supplier	die	Silicon (Si)	7440-21-3		6.586	mg	926822	17800				
				supplier	metallization	Aluminium (Al)	7429-90-5		0.058	mg	8162	157				
				supplier	metallization	Copper (Cu)	7440-50-8		0.171	mg	24064	462				
				supplier	metallization	Nickel (Ni)	7440-02-0		0.001	mg	141	3				
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.029	mg	4081	78				
				supplier	metallization	Titanium (Ti)	7440-32-6		0.007	mg	985	19				
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	141	3				
				supplier	Passivation	Silicon Nitride	12033-89-5		0.041	mg	5770	111				
				supplier	Passivation	Silicon Oxide	7631-86-9		0.212	mg	29834	573				
				Substrate (A293670)	M-011 Other inorganic materials	106.251	mg	supplier	BT-substrate	Thermosetting resin (Inorganic filler)	Proprietary		8.500	mg	80000	22973
supplier	BT-substrate	Glass cloth	65997-17-3						34.000	mg	320000	91893				
supplier	BT-substrate	Copper foil	7440-50-8						38.250	mg	360000	103379				
supplier	Solder mask	3-methoxy-3-methylbutylacetate	103429-90-9						5.313	mg	50000	14358				
supplier	Solder mask	Morpholinederivative	Trade secret						1.063	mg	10000	2872				
supplier	Solder mask	Barium Sulfate	7727-43-7						12.750	mg	120000	34460				
supplier	Solder mask	Talc containing no as bestiform fibers	14807-96-6						0.531	mg	5000	1436				
supplier	Solder mask	Dipropylene glycol monomethyl ether	34590-94-8						5.844	mg	55000	15794				
DAF (2100AC)	M-011 Other inorganic materials	3.890	mg					supplier	film	Copper (Cu)	7440-50-8		3.059	mg	786250	8286
								supplier	film	Silver (Ag)	7440-22-4		0.204	mg	52500	552
				supplier	film	2,2-dimethyl-1,3-propanediyl bismethacrylate	1985-51-9		0.165	mg	42500	447				
				supplier	film	4-allyl-2,6-bis (2,3-epoxypropyl)phenol; 4-allyl-	Trade secret		0.219	mg	56205	591				
				supplier	film	2-[[[2,2-bis[[[(1-oxoallyl)oxy]methyl]butoxy]met	94108-97-1		0.152	mg	39195	412				
				supplier	film	tert-butyl peroxyneodecanoate	26748-41-4		0.088	mg	22500	237				
				supplier	film	Hydroquinone	123-31-9		0.003	mg	850	9				
				Bonding wire (CuPd)	Precious metals	2.181	mg	supplier	Bonding wire	Copper (Cu)	7440-50-8		2.106	mg	965500	5691
supplier	Bonding wire	Palladium (Pd)	7440-05-3						0.068	mg	31000	183				
supplier	Bonding wire	Gold (Au)	78440-57-5						0.008	mg	3500	21				
Encapsulation (KE-G1250AAS)	M-011 Other inorganic materials	224.309	mg	supplier	Molding Compound	Epoxy resin	Trade secret		8.972	mg	40000	24250				
				supplier	Molding Compound	Silica(Fused)	60676-86-0,7631-86-9		204.121	mg	910000	551679				
				supplier	Molding Compound	Phenol resin	Trade secret		10.318	mg	46000	27887				
Solderballs (SACN305)	Solder	26.263	mg	supplier	Molding Compound	Carbon Black	1333-86-4		0.897	mg	4000	2425				
				supplier	Solder	Metallic Tin	7440-31-5		25.331	mg	964500	68461				
				supplier	Solder	Silver Atom	7440-22-4		0.788	mg	30000	2129				
				supplier	Solder	Metallic Copper	7440-50-8		0.131	mg	5000	355				
supplier	Solder	Nickel Element	7440-02-2		0.013	mg	500	35								